

# MATERIAL DECLARATION SHEET



Material Number	CRF2010 Series ( Cu)			
Product Line	Metal Plate Current Sensing Chip Resistors			
Compliance Date	2022/11/29			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Protective Coating	Epoxy	0.003555	Epoxy	29690-82-2	100 %	0.003555	15.39%
2	Resistive Body	Metal	0.013481	Copper	7440-50-8	100 %	0.013481	58.36%
3	Marking Layer	Epoxy	0.000014	Epoxy	29690-82-2	100 %	0.000014	0.06%
4	Cu Plating	Metal	0.005246	Copper(II) oxide	1317-38-0	100 %	0.005246	22.71%
5	Ni Plating	Metal	0.000425	Nickel	7440-02-0	100 %	0.000425	1.84%
6	Sn Plating	Metal	0.000379	Tin	7440-31-5	100 %	0.000379	1.64%
			Total weight	0.0231				

**This Document was updated on: 2022/11/29**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.